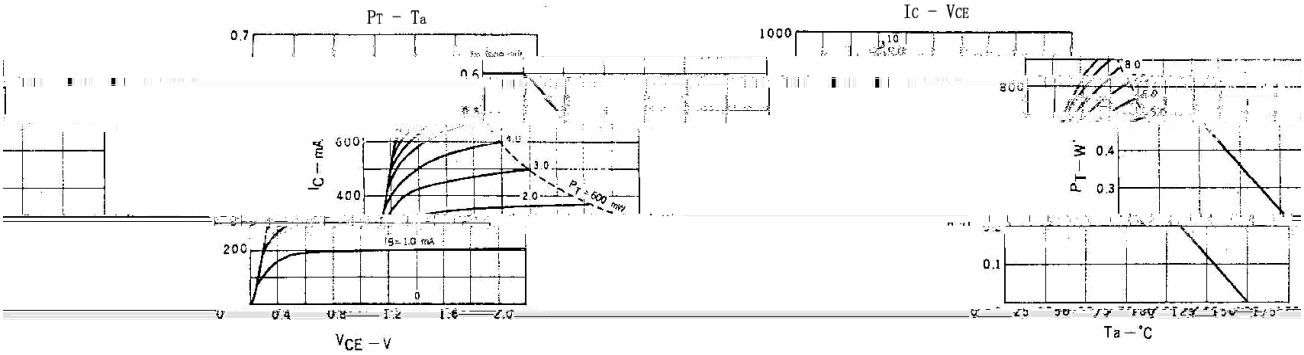
| Parameter | Symbol | Rating | Unit |
|---|---|---|---|
| Collector to Base Voltage | $V_{CBO}$ | 30 | V |
| Collector to Emitter Voltage | $V_{CEO}$ | 25 | V |
| Emitter to Base Voltage | $V_{EBO}$ | 5.0 | V |
| Collector Current - Continuous | $I_C$ | 700 | mA |
| Base Current - Continuous | $I_B$ | 150 | mA |
| Collector Power Dissipation | $P_C$ | 600 | mW |

## / Electrical Characteristic Curve



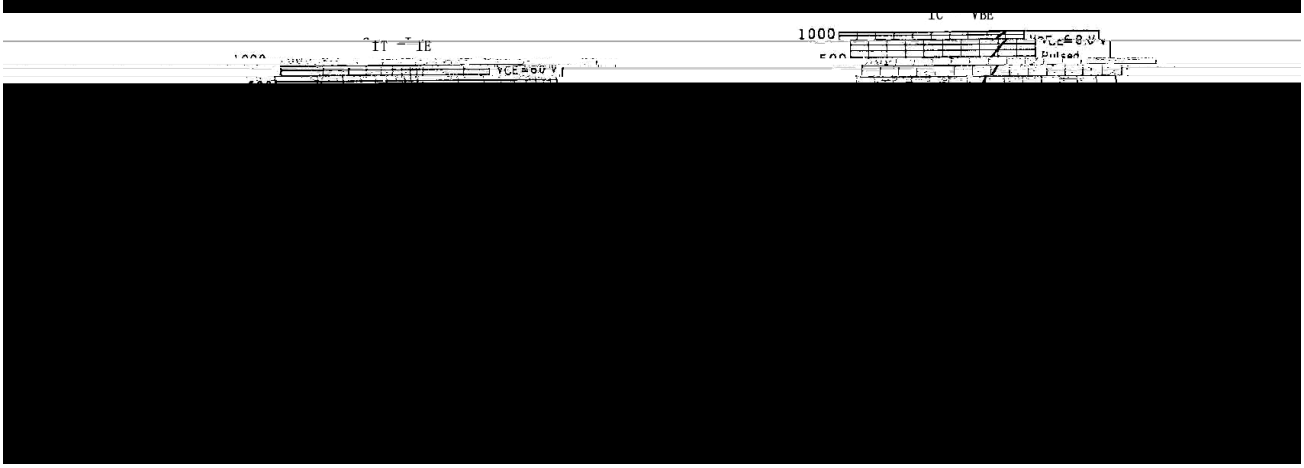

VCE(sat) – IC

VBE(sat) – IC

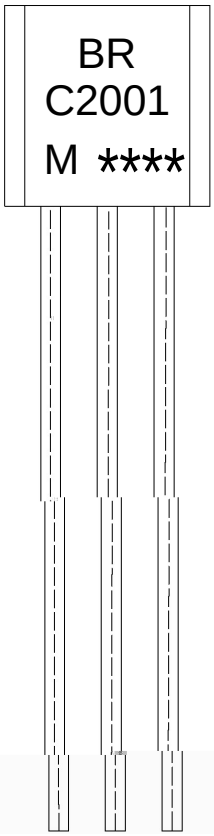
IC – VCE

hFE – IC





## / Marking Instructions




BR:

C2001

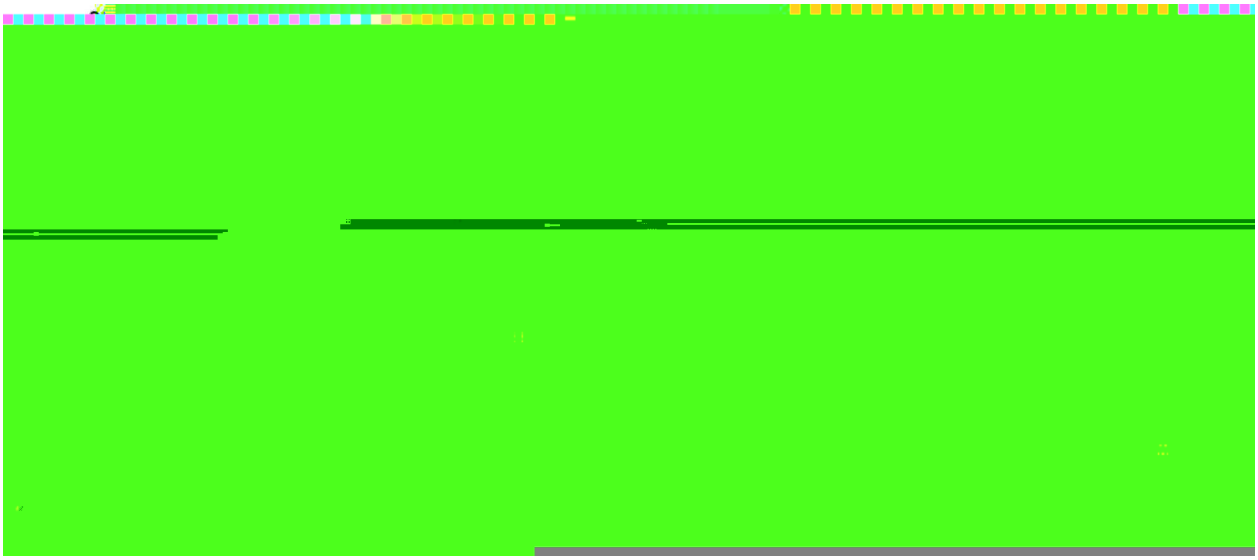
M: $h_{FE}$

****

Note:

| | |
|---|---|
| BR: | Company Code. |
| C2001: | Product Type. |
| M: | $h_{FE}$ Classifications Symbol |
| ****: | Lot No. Code,code change with Lot No. |

## ( ) / Temperature Profile for Dip Soldering(Pb-Free)



| | | | | | | | |
|---|---|---|---|---|---|---|---|
| | | | | | | Note: | |
| 1 | | 25 | 150 | | 60 90sec; | 1.Preheating:25~150 , Time:60~90sec. | |
| 2 | | 255±5 | | | 5±0.5sec; | 2.Peak Temp.:255±5 , Duration:5±0.5sec. | |
| 3 | | | | 2 10 /sec. | | 3. Cooling Speed: 2~10 /sec. | |

## / Resistance to Soldering Heat Test Conditions

| | | | |
|---|---|---|---|
| 270±5 | 10±1 sec. | Temp:270±5 | Time:10±1 sec |

## / Packaging SPEC.

/ BULK

dÊWÐ(37Ħqý